

v02.1210



GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

Typical Applications

The HMC213AMS8(E) is ideal for:

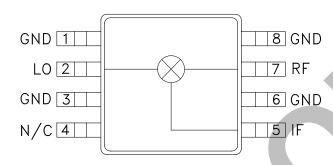
- Base Stations
- PCMCIA Transceivers
- Wireless Local Loop

Features

Ultra Small Package: MSOP8

Conversion Loss: 8.5 dB LO / RF Isolation: 40 dB

Functional Diagram



General Description

The HMC213AMS8(E) is a ultra miniature double-balanced mixer in 8 lead plastic surface mount package (MSOP). This passive MMIC mixer is constructed of GaAs Schottky diodes and novel planar transformer baluns on the chip. The device can be used as an upconverter, downconverter, biphase (de)modulator, or phase comparator. The consistent MMIC performance will improve system operation and assure regulatory compliance.

Electrical Specifications, $T_A = +25^{\circ}$ C, As a Function of LO Drive

Parameter	LO = +13 dBm IF = 100 MHz		LO = +10 dBm IF = 100 MHz			Units	
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Frequency Range, RF & LO		1.5 - 4.5			1.7 - 3.6		GHz
Frequency Range, IF		DC - 1.5			DC - 1.5		GHz
Conversion Loss		8.5	10		9	10.5	dB
Noise Figure (SSB)		8.5	10		9	10.5	dB
LO to RF Isolation	29	40		32	40		dB
LO to IF Isolation	27	35		26	35		dB
IP3 (Input)	16	19		14	18		dBm
1 dB Gain Compression (Input)	7	10		5	8		dBm

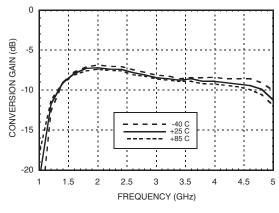


v02.1210

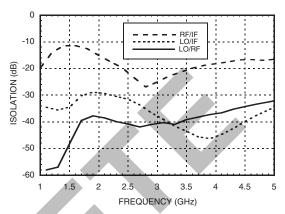


GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

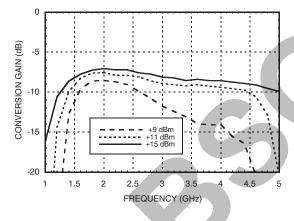
Conversion Gain vs. Temperature @ LO = +13 dBm



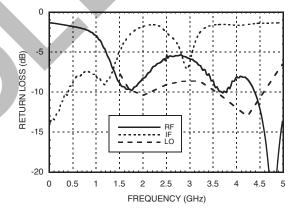
Isolation @ LO = +13 dBm



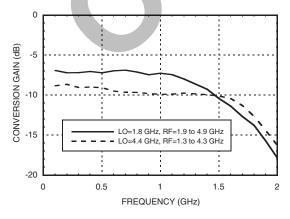
Conversion Gain vs. LO Drive



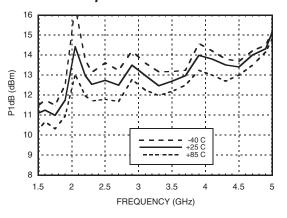
Return Loss @ LO = +13 dBm



IF Bandwidth @ LO = +13 dBm



P1dB vs. Temperature @ LO = +13 dBm



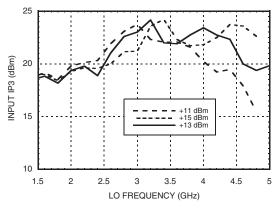


v02.1210

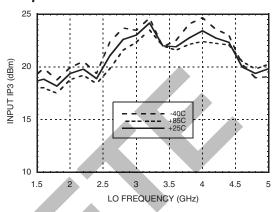


GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

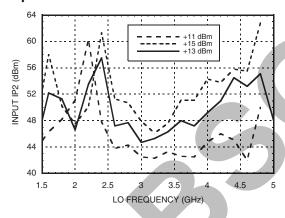
Input IP3 vs. LO Drive



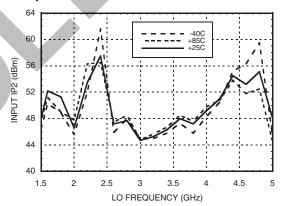
Input IP3 vs. Temperature @ LO = +13 dBm



Input IP2 vs. LO Drive



Input IP2 vs. Temperature @ LO = +13 dBm





v02.1210



GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	xx	12.7	20.8	19.8	76.2
1	13.4	0	39.8	38.9	56.2
2	73.8	78.2	66.5	82.2	68.8
3	93.8	89.2	92.2	82.4	89.0
4	>105	>105	>105	>105	>105

RF = 3.5 GHz @ -10 dBm LO = 3.6 GHz @ +13 dBm

All values in dBc below IF power level (-1RF + 1LO)

Harmonics of LO @ RF Port

LO Freq.	nLO Spur				
(GHz)	1	2	3	4	
1.5	40	30	62	57	
2.0	38	25	55	58	
2.5	41	28	34	61	
3.0	41	35	36	61	
3.5	38	45	52	62	
4.0	35	47	55	62	
4.5	33	50	65	73	
5.0	32	52	68	82	
10 :10 dBm					

LO = +13 dBr

Values in dBc below input LO level measured at RF Port.

Absolute Maximum Ratings

RF / IF Input	+13 dBm
111 / II IIIput	+10 dbiii
LO Drive	+27 dBm
Continuous Pdiss (T = 85 °C) (derate 10.6 mW/°C above 85 °C)	0.69 W
Thermal Resistance (Channel to package lead)	93.7 °C/W
Junction Temperature	150 °C
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

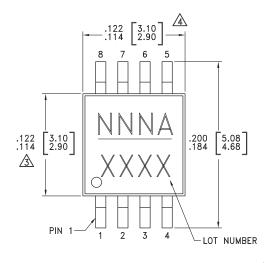


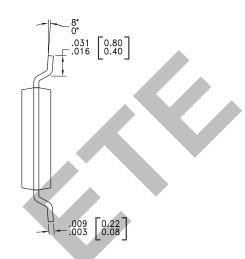
v02.1210

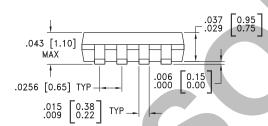


GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

Outline Drawing







NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- A DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC213AMS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	213A XXXX
HMC213AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	213A XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

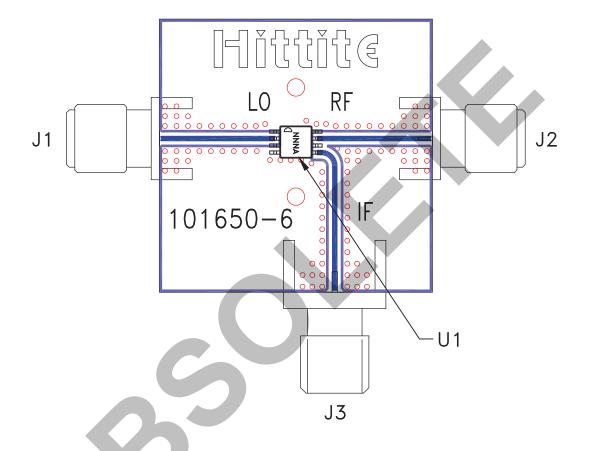


v02.1210



GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

Evaluation PCB



List of Materials for Evaluation PCB 103350 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC213AMS8(E) Mixer
PCB [2]	101650 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for RF Mixer category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below:

 M80C
 HMC337-SX
 F1763EVBI
 mamx-009646-23dbml
 HMC339-SX
 F1751NBGI
 CSM5T
 CHR3664-QEG
 NJM2552V-TE1

 HMC220BMS8GE
 HMC8192-SX
 LTC5569IUF#PBF
 HMC220BMS8GETR
 MAX2055EUP+TD
 M85C
 M74C
 CSM4TH
 HMC8191-SX

 CMD251C3
 MD-174-PIN
 CMD253C3
 HMC8192LG
 HMC553AG-SX
 HMC521A-SX
 HMC521ACHIPS
 HMC558A
 HMC553AG

 HMC8191
 MAMX-011023-SMB
 EMRS-1TR
 ADL5355ACPZ-R7
 HMC399MS8TR
 HMC141LH5
 HMC333TR
 HMC214MS8TR

 HMC175MS8TR
 HMC1043LC3TR
 F0552NLGI
 F1701NBGI
 F0502NLGI
 F1763NBGI
 MDS-189-PIN
 MAX2042AETP+
 MAX2032ETP+

 MAX2043ETX+
 CSM2-13
 CSM4T
 HMC1056LP4BETR
 LTC5510IUF#PBF
 LTC5553IUDB#TRMPBF